



Atty Docket No.: 1819.110

In re the PATENT application of

T.L. Ritzdorf et al

Examiner: Leader

Serial No.: 09/880,715

Group Art Unit: 2823

Filed: June 12, 2001

For: Method for Filling Recessed Micro-Structures with Metallization in the Production of a Microelectronic Device

INFORMATION DISCLOSURE STATEMENT

MAIL STOP: RCE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

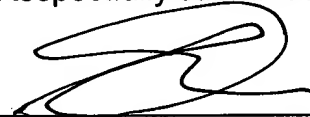
Pursuant to the duty imposed by 37 C.F.R. §1.56 to disclose information which may be material to the above-identified patent application, the Examiner's attention is directed to the documents listed on the enclosed Information Disclosure Statement. Copies of the documents listed are enclosed herewith.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or

otherwise remove any listed document as a competent reference against the claims of the present application.

The Commissioner is hereby authorized to charge any other fee due with this paper to Deposit Account No. 50-2449.

Respectfully submitted,



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